


# MATERIAL DECLARATION SHEET



Package Type	PTVS1-(066C-086C)-H			
Product Line	Semiconductor Products			
Compliance Date	21 <sup>th</sup> Jan 2022			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	0.1851	Amorphous Silica	60676-86-0	87.000	50.428	52.26
				Solid Epoxy Resin 1	Proprietary	4.600	0.170	
				Solid Epoxy Resin 2	Proprietary	4.490	0.145	
				Phenol Resin	Proprietary	2.700	0.855	
				Carbon Black	1333-86-4	0.700	0.314	
				Crystalline Silica	14808-60-7	0.510	0.350	
2	Leadframe	Copper Alloy	0.0618	Copper	7440-50-8	97.433	17.064	17.45
				Iron	7439-89-6	2.350	0.362	
				Phosphorus	7723-14-0	0.125	0.006	
				Zinc	7440-66-6	0.083	0.012	
				Lead	7439-92-1	0.010	0.002	
3	Clip	Copper Alloy	0.0360	Copper	7440-50-8	95.485	9.61226	10.17
				Silver	7440-22-4	4.500	0.55614	
				Iron	7439-89-6	0.005	0.00044	
				Lead	7439-92-1	0.005	0.00064	
				Zinc	7440-66-6	0.003	0.00024	
4	Chip	Silicon	0.0274	Phosphorous	7723-14-0	0.002	0.00005	7.74
				Silicon	7440-21-3	90.650	7.104	
				Nickel	7440-02-0	5.403	0.275	
				Aluminum	7429-90-5	3.815	0.354	
				Gold	7440-57-5	0.132	0.009	
5	Electrodes	Copper Alloy	0.0271	Copper	7440-50-8	95.485	7.22270	7.64
				Silver	7440-22-4	4.500	0.41789	
				Iron	7439-89-6	0.005	0.00033	
				Lead	7439-92-1	0.005	0.00048	
				Zinc	7440-66-6	0.003	0.00018	
6	Solder Paste	Solder	0.0139	Phosphorous	7723-14-0	0.002	0.00004	3.93
				Lead*	7439-92-1	92.500	3.7096	
				Tin	7440-31-5	5.000	0.1278	
7	Terminal Finish	Tin	0.0029	Silver	7440-22-4	2.500	0.09621	0.81
				Tin	7440-31-5	100.000	0.8051	
		Total weight	0.3542					

\* 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)